



Part Number
Key Word



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SAMPLE

STOCK CHECK

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Product List

Product Name	FF02S45SV1
Series Name	FF02S Series
Applicable FPC conductor spacing (mm)	0.3
Number of contacts	45
Connector type	Standard mounting type
Material of contact	Copper alloy
Finish of contact in connecting area	Partial Gold over Nickel
Finish of contact in PCB mounting area	Partial Gold over Nickel
Applicable FPC thickness (mm)	0.12
ZIF or Non-ZIF	ZIF
PCB mounted height (mm)	0.9
FPC entry angle	Right angle (Lower-side contact)

Packing Type	
Quantity in the standard packing	
Remarks	
Related Documents	 
Pair	

Notice:

1. The values specified in this web site are only for reference. The products and their specifications are subject to change without notice. Contact our sales staff for further information before considering or ordering any of our products.
For purchase, a product specification must be agreed upon.
2. Users are requested to provide protection circuits and redundancy circuits to ensure safety of the equipment, and sufficiently review the suitability of JAE's products to the equipment.
3. The products presented in this web site are designed for the uses recommended below. We strongly suggest you contact our sales staff when considering use of any of the products in any other way than the recommended applications or for a specific use that requires an extremely high reliability.

(1) Applications that require consultation:

- (i) Please contact us if you are considering use involving a quality assurance program that you specify or that is peculiar to the industry, such as:

Automotive electrical components, train control, telecommunications devices (mainline), traffic light control, electric power, combustion control, fire prevention or security systems, disaster evention equipment, etc.

- (ii) We may separately give you our support with a quality assurance program that you specify, when you think of a use such as :

Aviation or space equipment, submarine repeaters, nuclear power control systems, medical equipment for life support, etc.

- (2) Recommended applications include:

Computers, office appliances, telecommunications devices (terminals, mobile units), measuring equipment, audiovisual equipment, home electric appliances, factory automation equipment, etc

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6(DP)101CS
(ON: ONI/MYHO)各事用

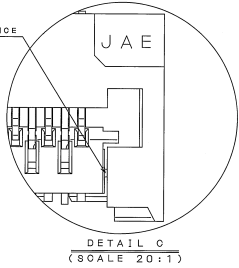
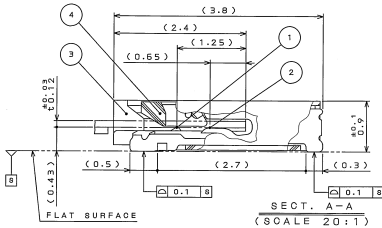
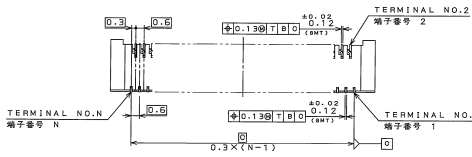
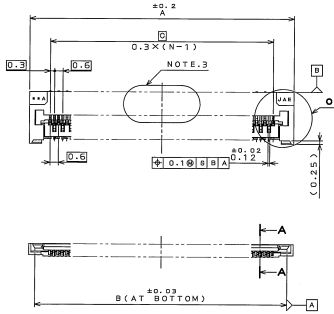
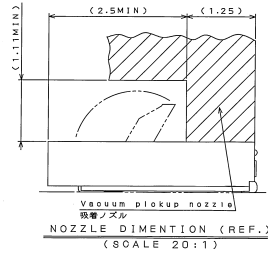


TABLE 1

PRODUCT No. 品番	A	B	C	D
FF02865SV1	22.2	21.31	19.2	21.24
FF02845SV1	19.2	18.31	16.2	18.24
FF02835SV1	16.2	15.31	13.2	15.24
FF02825SV1	13.2	12.31	10.2	12.24
FF02815SV1	10.2	9.31	7.2	9.24
FF02805SV1	7.2	6.31	4.2	6.24



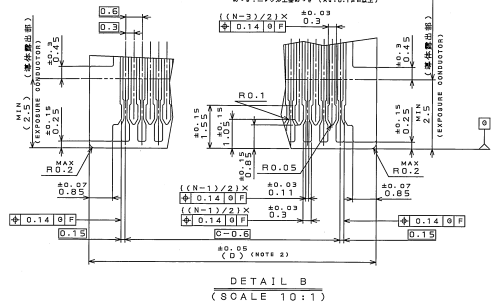
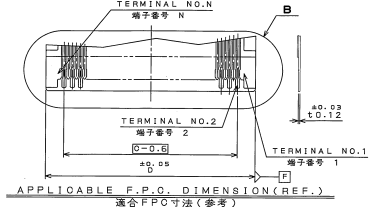
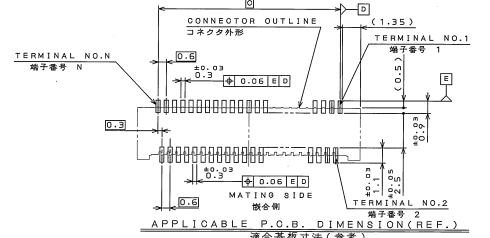
NOTE 1. REFER TO TABLE 2 ABOUT RECOMMENDED FPC COMPOSITION.
NOTE 2. TOLERANCE OF DIMENSION D IS RECOMMENDED TO BE ±0.05 IN ORDER TO IMPROVE PRECISION OF PITCH POSITIONING AND CONNECTION RELIABILITY.
NOTE 3. LOT NUMBER IS MARKED ON THE TOP CENTER PORTION OF THE CONNECTOR.

注1.推奨FPC構成はTABLE2参照のこと。
注2.寸法Dはピッチ方向の位置決め精度を高め信頼性を高めるために±0.05を推奨する。
注3.ロット番号がコネクタ上面中央部に表記される。

TABLE 2

COMPOSITION		RECOMMENDED
層名 GOLD PLATING	ELECTROLYSIS PLATING	推奨 0.1μm MIN
金めっき NICKEL PLATING	ELECTROLYSIS PLATING	SOFT TYPE IF AVAILABLE
ニッケルめっき COPPER	ROLLED MATERIAL	NOMINAL 18μm MAX
銅箔 ADHESIVE	THERMOSETTING ADHESIVE	NONE (RECOMMENDED)
接着剤 BASE FILM	POLYIMIDE	25μm
ベースフィルム ADHESIVE	THERMOSETTING ADHESIVE	30μm MAX
接着剤 REINFORCE PLATE	POLYIMIDE	-
補強板 補強板	ポリイミド	-

Rev.	年月日 DATE	Drawn DWN	Checked CHK	App'd APPD	App'd APPD	App'd APPD
2	19.04.2005	058469	ADDED NEW ITEMS	K.INOUE		04ASHIROUCHI
3	24.04.2005	058588	ADDED NEW ITEMS	K.INOUE		04ASHIROUCHI



NO.	DESCRIPTION	QUANTITY	MATERIAL	FINISH	REMARKS
4	ACTUATOR アクチュエータ	1	PPS		
3	BASE / REINFORCER ベース / 補強材	1	LOP		COLOR:BLACK / 色別:黒 UL94V-0
2	CONTRACT 2 コンタクト 2	(N-1)	COPPER ALLOY		COLOR:WHITE / 色別:白 UL94V-0
1	CONTRACT 1 コンタクト 1	(N-1)	COPPER ALLOY		

JAE CONNECTOR DIV. PROPRIETARY.
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